1360MHz Dual Output LVPECL Clock Synthesizer

8V43FS92432

DATA SHEET

General Description

The 8V43FS92432 is a 3.3V-compatible, PLL based clock synthesizer targeted for high performance clock generation in mid-range to high-performance telecom, networking, and computing applications. With output frequencies from 21.25MHz to 1360MHz and the support of two differential PECL output signals, the device meets the needs of the most demanding clock applications.

The 8V43FS92432 is a programmable high-frequency clock source (clock synthesizer). The internal PLL generates a high-frequency output signal based on a low-frequency reference signal. The frequency of the output signal is programmable and can be changed on the fly for frequency margining purpose.

The internal crystal oscillator uses the external quartz crystal as the basis of its frequency reference. Alternatively, a LVCMOS compatible clock signal can be used as a PLL reference signal. The frequency of the internal crystal oscillator is divided by a selectable divider and then multiplied by the PLL. Its output is scaled by a divider that is configured by either the I^2C or parallel interfaces. The crystal oscillator frequency $f_{XTAL,}$ the PLL pre-divider P, the feedback-divider M, and the PLL post-divider N determine the output frequency. The feedback path of the PLL is internal.

The PLL post-divider N is configured through either the I^2C or the parallel interfaces, and can provide one of six division ratios (2, 4, 8, 16, 32, 64). This divider extends the performance of the part while providing a 50% duty cycle. The high-frequency outputs, Q_A and Q_B, are differential and are capable of driving a pair of transmission lines terminated 50Ω to V_{CC} – 2.0 V. The second high-frequency output, Q_B, can be configured to run at either 1x or 1/2x of the clock frequency or the first output (Q_A). The positive supply voltage for the internal PLL is separated from the power supply for the core logic and output drivers to minimize noise induced jitter.

The configuration logic has two sections: I^2C and parallel. The parallel interface uses the values at the M[9:0], NA[2:0], NB, and P parallel inputs to configure the internal PLL dividers. The parallel programming interface has priority over the serial I^2C interface. The serial interface is I^2C compatible and provides read and write access to the internal PLL configuration registers. The lock state of the PLL is indicated by the LVCMOS-compatible LOCK output.

Features

- 21.25MHz to 1360MHz synthesized clock output signal
- Two differential, LVPECL-compatible high-frequency outputs
- Output frequency programmable through 2-wire I^2C bus or parallel interface
- On-chip crystal oscillator for reference frequency generation
- Alternative LVCMOS compatible reference clock input
- Synchronous clock stop functionality for both outputs
- LOCK indicator output (LVCMOS)
- LVCMOS compatible control inputs
- Fully integrated PLL
- 3.3-V power supply
- 48-lead LQFP
- 48-lead Pb-free package available
- SiGe Technology
- Ambient temperature range: –40°C to +85°C

Applications

- Programmable clock source for server, computing, and telecommunication systems
- Frequency margining
- Oscillator replacement

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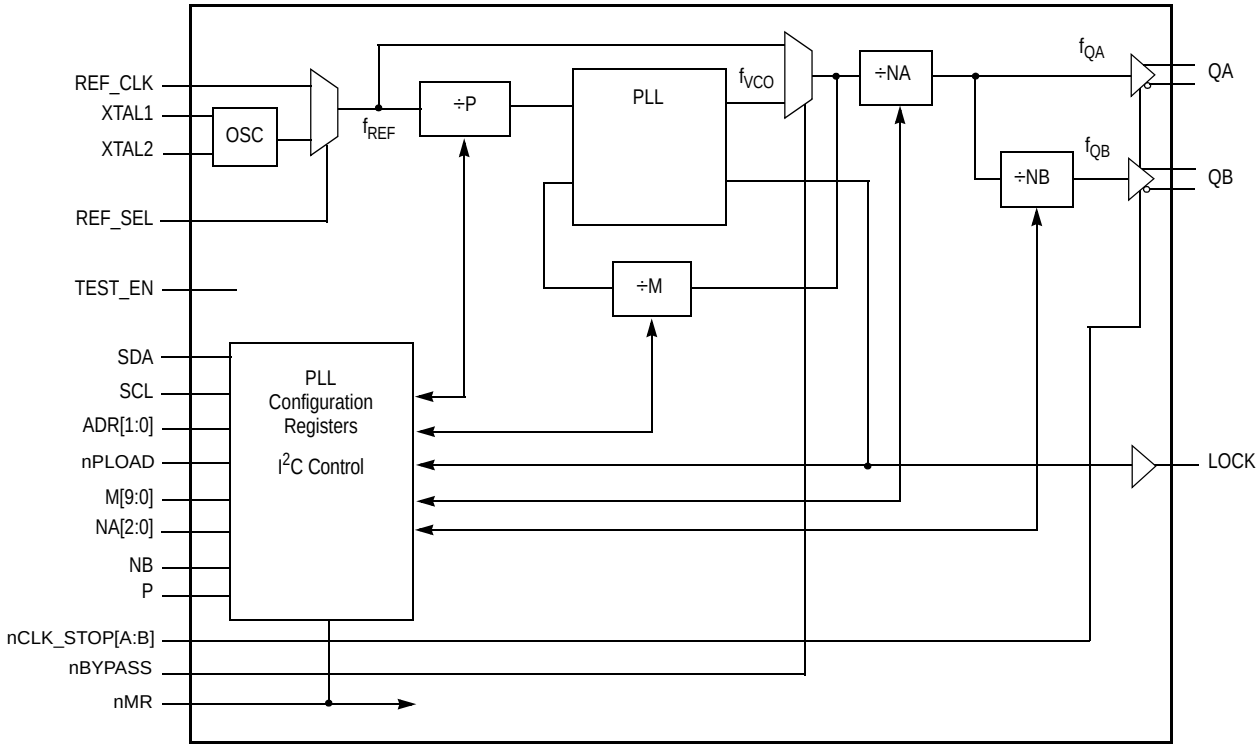
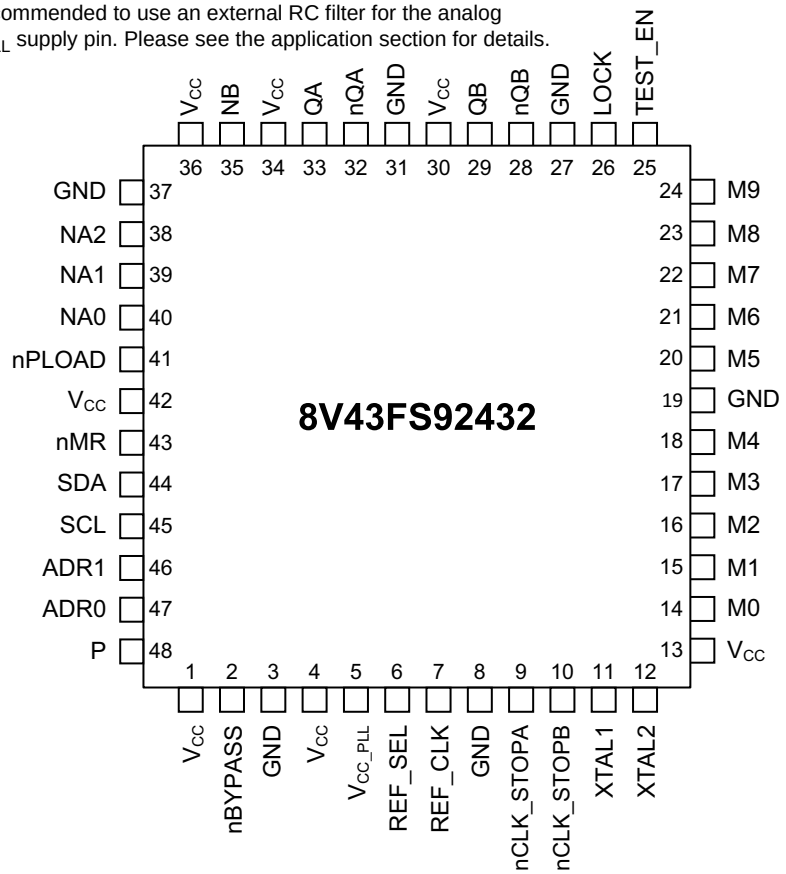
Block Diagram



Pin Assignment

It is recommended to use an external RC filter for the analog V_{CC_PLL} supply pin. Please see the application section for details.



48-pin, 7mm x 7mm LQFP Package

Pin Description and Characteristic Tables

Table 1. Pin Description Table

Number	Name	Type[1]		Description
1	V_{CC}	Power		Positive supply for I/O and core.
2	nBYPASS	Input	Pullup	Selects the static circuit bypass mode.
3	GND	Power		Power supply ground.
4	V_{CC}	Power		Positive supply for I/O and core.
5	V_{CC_PLL}	Power		Positive power supply for the PLL (analog power supply). It is recommended to use an external RC filter for the analog power supply pin V_{CC_PLL}.
6	REF_SEL	Input	Pullup	Selects the reference clock input.
7	REF_CLK	Input	Pulldown	PLL external single-ended reference input. LVCMOS/LVTTL interface levels.
8	GND	Power		Power supply ground.
9	nCLK_STOPA	Input	Pullup	Output Qx disable in logic low state.
10	nCLK_STOPB	Input	Pullup	Output Qx disable in logic low state.
11	XTAL1	Crystal Input		Crystal input.
12	XTAL2	Crystal Output		Crystal output.
13	V_{CC}	Power		Positive supply for I/O and core.
14	M0	Input	Pulldown	PLL feedback divider configuration.
15	M1	Input	Pulldown	PLL feedback divider configuration.
16	M2	Input	Pullup	PLL feedback divider configuration.
17	M3	Input	Pulldown	PLL feedback divider configuration.
18	M4	Input	Pullup	PLL feedback divider configuration.
19	GND	Power		Power supply ground.
20	M5	Input	Pullup	PLL feedback divider configuration.
21	M6	Input	Pullup	PLL feedback divider configuration.
22	M7	Input	Pullup	PLL feedback divider configuration.
23	M8	Input	Pullup	PLL feedback divider configuration.
24	M9	Input	Pulldown	PLL feedback divider configuration.
25	TEST_EN	Input	Pulldown	Factory test mode enable. This input must be set to logic low level in all applications of the device.
26	LOCK	Output	LVCMOS	PLL lock indicator.
27	GND	Power		Power supply ground.
28	nQB	Output	LVPECL	High frequency clock output.
29	QB	Output	LVPECL	High frequency clock output.
30	V_{CC}	Power		Positive supply for I/O and core.
31	GND	Power		Power supply ground.
32	nQA	Output	LVPECL	High frequency clock output.
33	QA	Output	LVPECL	High frequency clock output.

Table 1. Pin Description Table

Number	Name	Type[1]		Description
34	V_{CC}	Power		Positive supply for I/O and core.
35	NB	Input	Pulldown	PLL post-divider configuration for output QB.
36	V_{CC}	Power		Positive supply for I/O and core.
37	GND	Power		Power supply ground.
38	NA2	Input	Pulldown	PLL post-divider configuration for output QA.
39	NA1	Input	Pullup	PLL post-divider configuration for output QA.
40	NA0	Input	Pulldown	PLL post-divider configuration for output QA.
41	nPLOAD	Input	Pulldown	Selects the programming interface.
42	V_{CC}	Power		Positive supply for I/O and core.
43	nMR	Input	Pullup	Device master reset.
44	SDA	I/O	Pullup	I^2C data.
45	SCL	Input	Pullup	I^2C clock.
46	ADR1	Input	Pulldown	Selectable two bits of the I^2C slave address.
47	ADR0	Input	Pulldown	Selectable two bits of the I^2C slave address.
48	P	Input	Pullup	PLL pre-divider configuration.

NOTE 1. *Pullup and Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics table

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			2		pF
R_{PULLUP}	Input Pullup Resistor			75		kΩ
$R_{PULLDOWN}$	Input Pulldown Resistor			75		kΩ

Table 3. Function Table

Control	Default[1]	0	1
Inputs			
REF_SEL	1	Selects REF_CLK input as PLL reference clock	Selects the XTAL interface as PLL reference clock
M[9:0]	01 1111 0100b[2]	PLL feedback divider (10-bit) parallel programming interface	
NA[2:0]	010	PLL post-divider parallel programming interface. See Table 10	
NB	0	PLL post-divider parallel programming interface. See Table 11	
P	1	PLL pre-divider parallel programming interface. See Table 9	
nPLOAD	0	Selects the parallel programming interface. The internal PLL divider settings (M, NA, NB and P) are equal to the setting of the hardware pins. Leaving the M, NA, NB and P pins open (floating) results in a default PLL configuration with f_{OUT} = 250MHz. See application/programming section.	Selects the serial (I^2C) programming interface. The internal PLL divider settings (M, NA, NB and P) are set and read through the serial interface.
ADR[1:0]	00	Address Bit = 0	Address Bit = 1
SDA, SCL		See Programming the 8V43FS92432	
nBYPASS	1	PLL function bypassed $f_{QA} = f_{REF} \div N_A$ and $f_{QB} = f_{REF} \div (N_A \cdot N_B)$	PLL function enabled: $f_{QA} = (f_{REF} \div P) \cdot M \div N_A$ and $f_{QB} = (f_{REF} \div P) \cdot M \div (N_A \cdot N_B)$
TEST_EN	0	Application Mode. Test mode disabled.	Factory test mode is enabled
nCLK_STOP[A:B]	1	Output Q*x* is disabled in logic low state. Synchronous disable is only guaranteed if NB = 0.	Output Q*x* is synchronously enabled
nMR		The device is reset. The output frequency is zero and the outputs are asynchronously forced to logic low state. After releasing reset (upon the rising edge of nMR and independent on the state of nPLOAD), the 8V43FS92432 reads the parallel interface (M, NA, NB and P) to acquire a valid startup frequency configuration. See application/programming section.	The PLL attempts to lock to the reference signal. The t_{LOCK} specification applies.
Outputs			
LOCK		PLL is not locked	PLL is frequency locked

NOTE 1. Default states are set by internal input pull-up or pull-down resistors of 75kΩ.

NOTE 2. If f_{REF} = 16MHz, the default configuration will result in a output frequency of 250MHz.

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4. Absolute Maximum Ratings

Symbol	Characteristics		Min	Max	Unit
V_{CC}	Supply Voltage		-0.3	3.6	V
V_{IN}	DC Input Voltage		-0.3	V_{CC} + 0.3	V
V_I	Crystal Input Voltage		0	2	V
V_{OUT}	DC Output Voltage		-0.3	V_{CC} + 0.3	V
I_{IN}	DC Input Current			±20	mA
I_{OUT}	DC Output Current			±50	mA
T_S	Storage Temperature		-65	125	°C
T_{FUNC}	Functional Temperature Range		T_A = -40	T_A = +85	°C
T_J	Operating Junction Temperature			125	°C
HBM	ESD Human Body Model[1]			2000	V
CDM	ESD Charged Device Model[1]			500	V

NOTE 1. According to JEDEC/JS-001-2012/JESD22-C101E.

Table 5. DC Characteristics, V_{CC} = 3.3 V ± 5%, GND = 0V, T_J = –40°C to +85°C

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
LVCMOS Control Inputs (M[9:0], N[2:0], ADDR[1:0], NB, P, nCLK_STOP[A:B], nBYPASS, nMR, REF_SEL, TEST_EN, nPLOAD)						
V_{IH}	Input High Voltage	LVCMOS	2.0		V_{CC} + 0.3	V
V_{IL}	Input Low Voltage	LVCMOS			0.8	V
I_{IN}	Input Current[1]	V_{IN} = V_{CC} or GND			±200	µA
I^2C Inputs (SCL, SDA)						
V_{IH}	Input High Voltage	LVCMOS	2.0		V_{CC} + 0.3	V
V_{IL}	Input Low Voltage	LVCMOS			0.8	V
I_{IN}	Input Current	V_{IN} = V_{CC}			10	µA
		V_{IN} = GND			-150	µA
LVCMOS Output (LOCK)						
V_{OH}	Output High Voltage	I_{OH} = –4mA	2.4			V
V_{OL}	Output Low Voltage	I_{OL} = 4mA			0.4	V
I^2C Open Drain Output (SDA)						
V_{OL}	Input Low Voltage	I_{OL} = 4mA			0.4	V
Differential Clock Output QA, QB[2]						
V_{OH}	Output High Voltage	LVPECL	V_{CC} – 1.02		V_{CC} – 0.74	V
V_{OL}	Output Low Voltage	LVPECL	V_{CC} – 1.95		V_{CC} – 1.5	V
$V_{O(P-P)}$	Output Peak-to-Peak Voltage		0.5		1.0	V
Supply Current						
I_{CC_PLL}	PLL Supply Current	V_{CC_PLL} Pins, Output Unloaded			27	mA
I_{CC}	Power Supply Current	All V_{CC} Pins, Output Unloaded			138	mA

NOTE 1. Inputs have pull-down resistors affecting the input current.

NOTE 2. Outputs terminated 50Ω to V_{TT} = V_{CC} – 2V.

Table 6. Crystal Characteristics

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation			Fundamental		
Frequency		15		20	MHz
Equivalent Series Resistance (ESR)				50	Ω
Shunt Capacitance		5		7	pF
Load Capacitance (CL)			10		pF

Table 7. AC Characteristics, V_{CC} = 3.3 V ± 5%, GND = 0V, T_J = –40°C to +85°C)[1] [2]

Symbol	Parameter		Condition	Minimum	Typical	Maximum	Unit
f_{XTAL}	Crystal Interface Frequency Range			15	16	20	MHz
f_{REF}	FREF_EXT Reference Frequency Range			15		20	MHz
f_{VCO}	VCO Frequency Range[3]			1360		2720	MHz
f_{OUT}	Output Frequency[4]		N = ÷2	680		1360	MHz
			N = ÷4	340		680	MHz
			N = ÷8	170		340	MHz
			N = ÷16	85		170	MHz
			N = ÷32	42.5		85	MHz
			N = ÷64	21.25		42.5	MHz
f_{SCL}	Serial Interface (I^2C) Clock Frequency			0		0.4	MHz
$t_{P,MIN}$	Minimum Pulse Width (nPLOAD)			50			ns
DC	Output Duty Cycle[5]			45	50	55	%
$t_{SK(O)}$	Output-to-Output Skew[5]		NB = 0 ($f_{QA} = f_{QB}$)			38	ps
			NB = 1 ($f_{QA} = 2 \cdot f_{QB}$)			96	ps
t_r, t_f	Output Rise/Fall Time (QA, QB)[5]		20% to 80%	0.05		0.3	ns
t_r, t_f	Output Rise/Fall Time (SDA)		C_L = 400pF			250	ns
t_{P_EN}	Output Enable Time (nCLK_STOP[A:B] to QA, QB)		T_{Qx} = Output Period		$3.0 \cdot T_{Qx}$		ns
t_{P_DIS}	Output Disable Time (nCLK_STOP[A:B] to QA, QB)		T_{Qx} = Output Period		$3.0 \cdot T_{Qx}$		ns
$t_{JIT(CC)}$	Cycle-to-Cycle Jitter (RMS 1σ)[6]	NB = 0 (F_QA = F_QB)	N = ÷2			27	ps
			N = ÷4			23	ps
			N = ÷8			21	ps
			N = ÷16			28	ps
			N = ÷32			32	ps
			N = ÷64			42	ps
		NB = 1 (F_QA = 2 * F_QB)	N = ÷2			51	ps
			N = ÷4			38	ps
			N = ÷8			41	ps
			N = ÷16			44	ps
			N = ÷32			50	ps
			N = ÷64			57	ps
			N = ÷128, QB only			49	ps

Table 7. AC Characteristics, V_{CC} = 3.3 V ± 5%, GND = 0V, T_J = –40°C to +85°C)[1] [2]

Symbol	Parameter		Condition	Minimum	Typical	Maximum	Unit
$t_{JIT(PER)}$	Period Jitter (RMS 1σ)[7]	NB = 0 (F_QA = F_QB)	N = ÷2			6	ps
			N = ÷4			5	ps
			N = ÷8			4	ps
			N = ÷16			5	ps
			N = ÷32			6	ps
			N = ÷64			8	ps
		NB = 1 (F_QA = 2 * F_QB)	N = ÷2			16	ps
			N = ÷4			12	ps
			N = ÷8			14	ps
			N = ÷16			12	ps
			N = ÷32			12	ps
			N = ÷64			14	ps
			N = ÷128, QB only			13	ps
BW	PLL Closed Loop Bandwidth[8]		P = ÷2		150		kHz
			P = ÷4		100		kHz
t_{LOCK}	Maximum PLL Lock Time				10		ms

NOTE 1. AC characteristics apply for parallel output termination of 50Ω to $V_{TT} = V_{CC} – 2V$.

NOTE 2. Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 3. The input frequency f_{XTAL}, the PLL divider M and P must match the VCO frequency range: $f_{VCO} = f_{XTAL} \cdot M \div P$. The feedback divider M is limited to $170 \leq M \leq 340$ (for P = 2) and $340 \leq M \leq 680$ (for P = 4) for stable PLL operation.

NOTE 4. Output frequency for Q_A, Q_B if $N_B = 0$. With $N_B = 1$ the Q_B output frequency is half of the Q_A output frequency.

NOTE 5. Unless specify otherwise, electrical characterization is performed with the below output frequencies: 21.875, 30.626, 39.375, 45, 62.5, 80, 92.5, 127.5, 162.5, 190, 260, 330, 390, 530, 670 800, 1080, 1360MHz and f_{REF} = 16MHz.

NOTE 6. Maximum cycle jitter measured at the lowest VCO frequency.

NOTE 7. Maximum cycle period measured at the lowest VCO frequency.

NOTE 8. –3 dB point of PLL transfer characteristics.

Output Frequency Configuration

The 8V43FS92432 is a programmable frequency source (synthesizer) and supports an output frequency range of 21.25MHz – 1360MHz. The output frequency f_{OUT} is a function of the reference frequency f_{REF} and the three internal PLL dividers P, M, and N. f_{OUT} can be represented by this formula:

$$f_{OUT} = (f_{REF} \div P) \cdot M \div (N_{A,\,B}) \quad (1)$$

The M, N and P dividers require a configuration by the user to achieve the desired output frequency. The output divider, N_A determines the achievable output frequency range (see Table 8). The PLL feedback-divider M is the frequency multiplication factor and the main variable for frequency synthesis. For a given reference frequency f_{REF}, the PLL feedback-divider M must be configured to match the specified VCO frequency range in order to achieve a valid PLL configuration:

$$f_{VCO} = (f_{REF} \div P) \cdot M \text{ and} \quad (2)$$

$$1360 \le f_{VCO} \le 2720 \quad (3)$$

The output frequency may be changed at any time by changing the value of the PLL feedback divider M. The smallest possible output frequency change is the synthesizer granularity G (difference in f_{OUT} when incrementing or decrementing M). At a given reference frequency, G is a function of the PLL pre-divider P and post-divider N:

$$G = f_{REF} \div (P \cdot N_{A,B}) \quad (4)$$

The N_B divider configuration determines if the output Q_B generates a 1:1 or 2:1 frequency copy of the Q_A output signal. The purpose of the PLL pre-divider P is to situated the PLL into the specified VCO frequency range f_{VCO} (in combination with M). For a given output frequency, P = 4 results in a smaller output frequency granularity G, P = 2 results a larger output frequency granularity G and also increases the PLL bandwidth compared to the P = 2 setting.

The following example illustrates the output frequency range of the 8V43FS92432 using a 16MHz reference frequency.

Table 8. Frequency Ranges (f_{REF} = 16 MHz)

f_{OUT} (Q_A) [MHz]	N_A	M	P	G [MHz]
680 – 1360	N_A = 2	170 – 340	2	4
		340 – 680	4	2
340 – 680	N_A = 4	170 – 340	2	2
		340 – 680	4	1
170 – 340	N_A = 8	170 – 340	2	1
		340 – 680	4	0.5
85 – 170	N_A = 16	170 – 340	2	0.5
		340 – 680	4	0.25
42.5 – 85	N_A = 32	170 – 340	2	0.25
		340 – 680	4	0.125
21.25 – 42.5	N_A = 64	170 – 340	2	0.125
		340 – 680	4	0.0625

Example Output Frequency Configuration

If a reference frequency of 16MHz is available, an output frequency at Q_A of 250MHz and a small frequency granularity is desired, the following steps would be taken to identify the appropriate P, M, and N configuration:

1. Use Table 8 to select the output divider, N_A, that matches the desired output frequency or frequency range. According to Table 8, a target output frequency of 250MHz falls in the f_{OUT} range of 170MHz – 340MHz and requires to set N_A = 8.
2. Calculate the VCO frequency $f_{VCO} = f_{OUT} \cdot N_A$, which is 2000MHz in this example.
3. Determine the PLL feedback divider: M = $f_{VCO} \div P$.
   The smallest possible output granularity in this example calculation is 500kHz (set P = 4). M calculates to a value of 2000 ÷ 4 = 500.
4. Configure the 8V43FS92432 with the obtained settings:
   M[9:0] = 0111110100b(binary number for M = 500)
   N_A[2:0] = 010(÷8 divider, see Table 10)
   P = 1 (÷4 divider, see Table 9)
   N_B = 0 ($f_{OUT, QB} = f_{OUT, QA}$)
5. Use either parallel or serial interface to apply the setting. The I^2C configuration byte for this examples are:
   PLL_H = 01010010b and PLL_L = 11110100b.
   See Table 15 and Table 16 for register maps.

PLL Divider Configuration

Table 9. Pre-PLL Divider P

P	Value
0	$f_{REF} \div 2$
1	$f_{REF} \div 4$

Table 10. Post-PLL Divider N_A

N_{A0}	N_{A1}	N_{A2}	f_{OUT} (Q_A)
0	0	0	$f_{VCO} \div 2$
0	0	1	$f_{VCO} \div 4$
0	1	0	$f_{VCO} \div 8$
0	1	1	$f_{VCO} \div 16$
1	0	0	$f_{VCO} \div 32$
1	0	1	$f_{VCO} \div 64$

Table 11. Post-PLL Divider N_B

N_B	Value
0	$f_{OUT, QB} = f_{OUT, QA}$
1	$f_{OUT, QB} = f_{OUT, QA} \div 2$

Programming the 8V43FS92432

The 8V43FS92432 has a parallel and a serial configuration interface. The purpose of the parallel interface is to directly configure the PLL dividers through hardware pins without the overhead of a serial protocol. At device startup, the device always obtains an initial PLL frequency configuration through the parallel interface. The parallel interface does not support reading the PLL configuration.

The serial interface is I^2C compatible. It allows reading and writing devices settings by accessing internal device registers. The serial interface is designed for host-controller access to the synthesizer frequency settings for instance in frequency-margining applications.

Using the Parallel Interface

The parallel interface supports write-access to the PLL frequency setting directly through 15 configuration pins (P, M[9:0], NA[2:0], and NB). The parallel interface must be enabled by setting nPLOAD to logic low level. During $nPLOAD^- = 0$, any change of the logical state of the P, M[9:0], NA[2:0], and NB pins will immediately affect the internal PLL divider settings, resulting in a change of the internal VCO-frequency and the output frequency. The parallel interface mode disables the I^2C write-access to the internal registers; however, I^2C read-access to the internal configuration registers is enabled.

Upon startup, when the device reset signal is released (rising edge of the nMR signal), the device reads its startup configuration through the parallel interface and independent on the state of nPLOAD. It is recommended to provide a valid PLL configuration for startup. If the parallel interface pins are left open, a default PLL configuration will be loaded. After the low-to-high transition of nPLOAD, the configuration pins have no more effect and the configuration registers are made accessible through the serial interface.

Table 12. PLL Feedback-Divider Configuration (M)

Feedback Divider M	9	8	7	6	5	4	3	2	1	0
Pin	M9	M8	M7	M6	M5	M4	M3	M2	M1	M0
Default	0	1	1	1	1	1	0	1	0	0

Table 13. PLL Pre/Post-Divider Configuration (N, P)

Post-Div NA	2	1	0
Pin	NA2	NA1	NA0
Default	0	1	0

Post-Div NB	NB
Pin	NB
Default	0

Pre-Div P	P
Pin	P
Default	1

Using the I^2C Interface

nPLOAD = 1 enables the programming and monitoring of the internal registers through the I^2C interface. Device register access (write and read) is possible through the 2-wire interface using SDA (configuration data) and SCL (configuration clock) signals. The 8V43FS92432 acts as a slave device at the I^2C bus. For further information on I^2C it is recommended to refer to the I^2C bus specification (version 2.1).

nPLOAD = 0 disables the I^2C-write-access to the configuration registers and any data written into the register is ignored. However, the 8V43FS92432 is still visible at the I^2C interface and I^2C transfers are acknowledged by the device. Read-access to the internal registers during nPLOAD = 0 (parallel programming mode) is supported.

Note that the device automatically obtains a configuration using the parallel interface upon the release of the device reset (rising edge of nMR) and independent on the state of nPLOAD. Changing the state of the nPLOAD input is not supported when the device performs any transactions on the I^2C interface.

Programming Model and Register Set

The synthesizer contains two fully accessible configuration registers (PLL_L and PLL_H) and a write-only command register (CMD). Programming the synthesizer frequency through the I^2C interface requires two steps: 1) writing a valid PLL configuration to the configuration registers and 2) loading the registers into the PLL by an I^2C command. The PLL frequency is affected as a result of the second step. This two-step procedure can be performed by a single I^2C transaction or by multiple, independent I^2C transactions. An alternative way to achieve small PLL frequency changes is to use the increment or decrement commands of the synthesizer, which have an immediate effect on the PLL frequency.

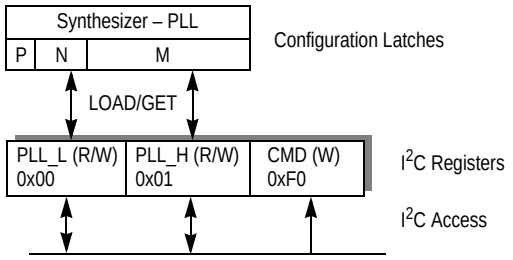


Figure 1. . I^2C Mode Register Set

Figure 1. illustrates the synthesizer register set. PLL_L and PLL_H store a PLL configuration and are fully accessible (Read/Write) by the I^2C bus. CMD (Write only) accepts commands (LOAD, GET, INC, DEC) to update registers and for direct PLL frequency changes.

Set the synthesizer frequency:

1) Write the PLL_L and PLL_H registers with a new configuration (see Table 15 and Table 16 for register maps)
2) Write the LOAD command to update the PLL dividers by the current PLL_L, PLL_H content.

Read the synthesizer frequency:

1) Write the GET commands to update the PLL_L, PLL_H registers by the PLL divider setting
2) Read the PLL_L, PLL_H registers through I^2C

Change the synthesizer frequency in small steps:

1) Write the INC or DEC command to change the PLL frequency immediately. Repeat at any time if desired.

LOAD and GET are inverse command to each other. LOAD updates the PLL dividers and GET updates the configuration registers. A fast and convenient way to change the PLL frequency is to use the INC (increment M) and DEC (decrement M) commands of the synthesizer. INC (DEC) directly increments (decrements) the PLL-feedback divider M and immediately changes the PLL frequency by the smallest step G (see Table 8 for the frequency granularity G). The INC and DEC commands are designed for multiple and rapid PLL frequency changes as required in frequency margining applications. INC and DEC do not require the user to update the PLL dividers by the LOAD command, INC and DEC do not update the PLL_L and PLL_H registers either (use LOAD for an initial PLL divider setting and, if desired, use GET to read the PLL configuration). Note that the synthesizer does not check any boundary conditions such as the VCO frequency range. Applying the INC and DEC commands could result in invalid VCO frequencies (VCO frequency beyond lock range).

Register Maps

Table 14. Configuration Registers

Address	Name	Content	Access
0x00	PLL_L	Least significant 8 bits of M	R/W
0x01	PLL_H	Most significant 2 bits of M, P, N_A, N_B, and lock state	R/W
0xF0	CMD	Command register (write only)	W only

Register 0x00 (PLL_L) contains the least significant bits of the PLL feedback divider M.

Table 15. PLL_L (0x00, R/W) Register

Bit	7	6	5	4	3	2	1	0
Name	M7	M6	M5	M4	M3	M2	M1	M0

Register content:
M[7:0] PLL feedback-divider M, bits [7–0]

Register 0x01 (PLL_H) contains the two most significant bits of the PLL feedback divider M, four bits to control the PLL post-dividers N and the PLL pre-divider P. The bit 0 in PLL_H register indicates the lock condition of the PLL and is set by the synthesizer automatically. The LOCK state is a copy of the PLL lock signal output (LOCK). A write-access to LOCK has no effect.

Table 16. PLL_H (0x01, R/W) Register

Bit	7	6	5	4	3	2	1	0
Name	M9	M8	NA2	NA1	NA0	NB	P	LOCK

Register content:

M[9:8] PLL feedback-divider M, bits 9–8
NA[2:0] PLL post-divider N_A, see Table 10
NB PLL post-divider N_B, see Table 11
P PLL pre-divider P, see Table 9
LOCK Copy of LOCK output signal (read-only)

Note that the LOAD command is required to update the PLL dividers by the content of both PLL_L and PLL_H registers.

Register 0xF0 (CMD) is a write-only command register.
The purpose of CMD is to provide a fast way to increase or decrease the PLL frequency and to update the registers. The register accepts four commands, INC (increment M), DEC (decrement M), LOAD and GET (update registers). It is recommended to write the INC, DEC commands only after a valid PLL configuration is achieved. INC and DEC only affect the M-divider of the PLL (PLL feedback). Applying INC and DEC commands can result in a PLL configuration beyond the specified lock range and the PLL may loose lock. The 8V43FS92432 does not verify the validity of any commands such as LOAD, INC, and DEC. The INC and DEC commands change the PLL feedback divider without updating PLL_L and PLL_H.

Table 17. CMD (0xF0): PLL Command (Write-Only)

Command	Op-Code	Description
INC	xxxx0001b (0x01)	Increase internal PLL frequency M= M+1
DEC	xxxx0010b (0x02)	Decrease internal PLL frequency M= M-1
LOAD	xxxx0100b (0x04)	Update the PLL divider config. PLL divider M, N, P= PLL_L, PLL_H
GET	xxxx1000b (0x08)	Update the configuration registers PLL_L, PLL_H= PLL divider M, N, P

I^2C — Register Access in Parallel Mode

The 8V43FS92432 supports the configuration of the synthesizer through the parallel interlace (nPLOAD = 0) and serial interface (nPLOAD = 1). Register contents and the divider configurations are not changed when the user switches from parallel mode to serial mode. However, when switching from serial mode to parallel mode, the PLL dividers immediately reflect the logical state of the hardware pins M[9:0], NA[2:0], NB, and P.

Applications using the parallel interface to obtain a PLL configuration can use the serial interface to verify the divider settings. In parallel mode (nPLOAD = 0), the 8V43FS92432 allows read-access to PLL_L and PLL_H through I^2C (if nPLOAD = 0, the current PLL configuration is stored in PLL_L, PLL_H. The GET command is not necessary and also not supported in parallel mode). After changing from parallel to serial mode (nPLOAD = 1), the last PLL configuration is still stored in PLL_L, PLL_H. The user now has full write and read access to both configuration registers through the I^2C bus and can change the configuration at any time.

Table 18. PLL Configuration in Parallel and Serial Modes

PLL Configuration	Parallel	Serial (Registers PLL_L, PLL_H)
M[9:0]	Set pins M9–M0	M[9:0] (R/W)
NA[2:0]	Set pins NA2...NA0	NA[2:0] (R/W)
NB	Set pin NB	NB (R/W)
P	Set pin P	P (R/W)
LOCK status	LOCK pin 26	LOCK (Read only)

Programming the I²C Interface

Table 19. I²C Slave Address

Bit	7	6	5	4	3	2	1	0
Value	1	0	1	1	0	Pin ADR1	Pin ADR0	R/W

The 7-bit I²C slave address of the 8V43FS92432 synthesizer is a combination of a 5-bit fixed addresses and two variable bits which are set by the hardware pins ADR[1:0]. Bit 0 of the 8V43FS92432 slave address is used by the bus controller to select either the read or write mode0' indicates a transmission (I²C-WRITE) to the 8V43FS92432 1' indicates a request for data (I²C-READ) from the synthesizer. The hardware pins ADR1 and ADR0 and should be individually set by the user to avoid address conflicts of multiple 8V43FS92432 devices on the same I²C bus.

Write Mode (R/W = 0)

The configuration registers are written by the bus controller by the initiation of a write transfer with the 8V43FS92432 slave address (first byte), followed by the address of the configuration register (second byte: 0x00, 0x01 or 0xF0), and the configuration data byte (third byte). This transfer may be followed by writing more registers by sending the configuration register address followed by one data byte. Each byte sent by the bus controller is acknowledged by the 8V43FS92432. The transfer ends by a stop bit sent by the bus controller. The number of configuration data bytes and the write sequence are not restricted.

Table 20. Complete Configuration Register Write Transfer

1 bit	7 bits	1 bit	1 bit	8 bits	1 bit	8 bits	1 bit	8 bits	1 bit	8 bits	1 bit	1 bit
Start	**Slave Address**	**R/W**	**ACK**	**&PLL_H**	**ACK**	**Config-Byte 1**	**ACK**	**&PLL_L**	**ACK**	**Config-Byte 2**	**ACK**	**Stop**
	10110xx[1]	0		0x01		Data		0x00		Data		
Master	Master	Master	Slave	Master	Slave	Master	Slave	Master	Slave	Master	Slave	Master

NOTE 1. xx = state of ADR1, ADR0 pins

Read Mode (R/W = 1)

The configuration registers are read by the bus controller by the initiation of a read transfer. The 8V43FS92432 supports read transfers immediately after the first byte without a change in the transfer direction. Immediately after the bus controller sends the slave address, the 8V43FS92432 acknowledges and then sends both configuration register PLL_L and PLL_H (back-to-back) to the bus controller. The CMD register cannot be read. In order to read the two synthesizer registers and the current PLL configuration setting, the user can 1) read PLL_L, PLL_H, write the GET command (loads the current configuration into PLL_L, PLL_H) and read PLL_L, PLL_H again. Note that the PLL_L, PLL_H registers and divider settings may not be equivalent after the following cases:

a. Writing the INC command

b. Writing the DEC command

c. Writing PLL_L, PLL_H registers with a new configuration and not writing the LOAD command.

Table 21. Configuration Register Read Transfer

1 bit	7 bits	1 bit	1 bit	8 bits	1 bit	8 bits	1 bit	1 bit
Start	**Slave Address**	**R/W**	**ACK**	**PLL_L**	**ACK**	**PLL_H**	**ACK**	**Stop**
	10110xx[1]	1		Data		Data		
Master	Master	Master	Slave	Slave	Master	Slave	Master	Slave

NOTE 1. xx = state of ADR1, ADR0 pins

Device Startup

General Device Configuration

It is recommended to reset the 8V43FS92432 during or immediately after the system powers up (nMR = 0). The device acquires an initial PLL divider configuration through the parallel interface pins M[9:0], NA[2:0], N, and P[1] with the low-to-high transition of nMR[2]. PLL frequency lock is achieved within the specified lock time (t_{LOCK}) and is indicated by an assertion of the LOCK signal which completes the startup procedure. It is recommended to disable the outputs (nCLK_STOP[A:B] = 0) until PLL lock is achieved to suppress output frequency transitions. The output frequency can be reconfigured at any time through either the parallel or the serial interface.

Note that a PLL configuration obtained by the parallel interface can be read through I^2C independent on the current programming mode (parallel or serial). Refer to I2C — Register Access in Parallel Mode for additional information on how to read a PLL startup configuration through the I^2C interface.

Starting-Up Using the Parallel Interface

The simplest way to use the 8V43FS92432 is through the parallel interface. The serial interface pins (SDA, SDL, and ADDR[1:0]) can be left open and nPLOAD is set to logic low. After the release of nMR and at any other time the PLL/output frequency configuration is directly set to through the M[9:0], NA[2:0], NB, and P pins.

Start-Up Using the Serial (I^2C) Interface

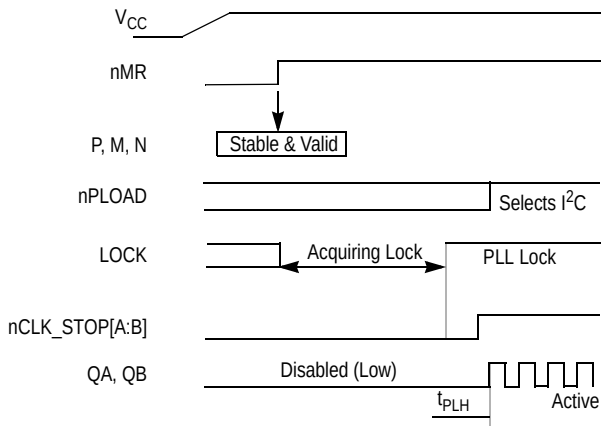


Figure 2. Start-Up Using I^2C Interface

Set nPLOAD = 1, nCLK_STOP[A:B] = L and leave the parallel interface pins (M[9:0], NA[2:0], N, and P) open. The PLL dividers are configured by the default configuration at the low-to-high transition of nMR. This initial PLL configuration can be re-programmed to the final VCO frequency at any time through the serial interface. After the PLL achieved lock at the desired VCO frequency, enable the outputs by setting nCLK_STOP[A:B] = H. PLL lock and re-lock (after any configuration change through M or P) is indicated by LOCK being asserted.

LOCK Detect

The LOCK detect circuitry indicates the frequency-lock status of the PLL by setting and resetting the pin LOCK and register bit LOCK simultaneously. The LOCK status is asserted after the PLL acquired frequency lock during the startup and is immediately de-asserted when the PLL lost lock, for instance when the reference clock is removed. The PLL may also loose lock when the PLL feedback-divider M or pre-divider P is changed or the DEC/INC command is issued. The PLL may not loose lock as a result of slow reference frequency changes. In any case of loosing LOCK, the PLL attempts to re-lock to the reference frequency. LOCK and re-lock of the PLL is indicated by the LOCK signal after a delay of TBD cycles to prevent signaling temporary PLL locks during frequency transitions.

Output Clock Stop

Asserting nCLK_STOP[A:B] will stop the respective output clock in logic low state. The nCLK_STOP[A:B] control is internally synchronized to the output clock signal, therefore, enabling and disabling outputs does not produce runt pulses. See Figure 3.. The clock stop controls of the QA and QB outputs are independent on each other. If the QB runs at half of the QA output frequency and both outputs are enabled at the same time, the first clock pulse of QA may not appear at the same time of the first QB output. (See Figure 4..) Coincident rising edges of QA and QB stay synchronous after the assertion and de-assertion of the nCLK_STOP[A:B] controls. Asserting nMR always resets the output divider to a logic low output state, with the risk of producing an output runt pulse.

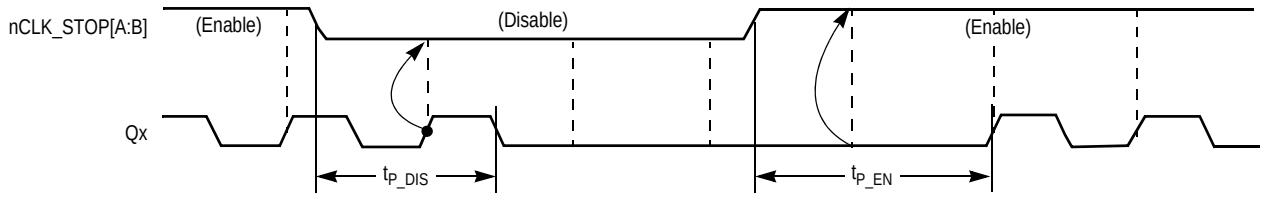


Figure 3. Clock Stop Timing for NB = 0 ($f_{QA} = f_{QB}$)

1. The parallel interface pins M[9:0], NA[2:0], N, and P may be left open (floating). In this case the initial PLL configuration will have the default setting of M = 500, P = 1, NA[2:0] = 010, NB = 0, resulting in an internal VCO frequency of 2000MHz (f_{ref} = 16 MHz) and an output frequency of 250 MHz.
2. The initial PLL configuration is independent on the selected programming mode (nPLOAD low or high).

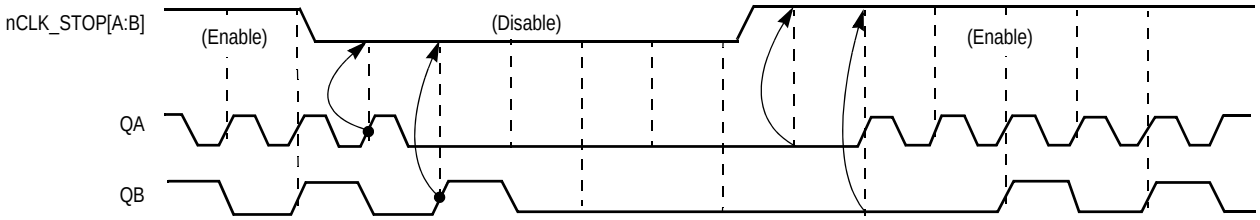


Figure 4. Clock Stop Timing for NB = 1 (f_{QA} = 2 f_{QB})

Frequency Operating Range

Table 22. 8V43FS92432 Frequency Operating Range for P = 2

		f_{VCO} [MHz] (Parameter: f_{REF} in MHz)				Output Frequency for f_{XTAL} = 16MHz (Parameter N)					
M	**M[9:0]**	**15**	**16**	**18**	**20**	**2**	**4**	**8**	**16**	**32**	**64**
170	0010101010		1360	1530	1700	680	340	170	85	42.50	21.25
180	0010110100		1440	1620	1800	720	360	180	90	45.00	22.50
190	0010111110	1425	1520	1710	1900	760	380	190	95	47.50	23.75
200	0011001000	1500	1600	1800	2000	800	400	200	100	50.00	25.00
210	0011010010	1575	1680	1890	2100	840	420	210	105	52.50	26.25
220	0011011100	1650	1760	1980	2200	880	440	220	110	55.00	27.50
230	0011100110	1725	1840	2070	2300	920	460	230	115	57.50	28.75
240	0011110000	1800	1920	2160	2400	960	480	240	120	60.00	30.00
250	0011111010	1875	2000	2250	2500	1000	500	250	125	62.50	31.25
260	0100000100	1950	2080	2340	2600	1040	520	260	130	65.00	32.50
270	0100001110	2025	2160	2430	2700	1080	540	270	135	67.50	33.75
280	0100011000	2100	2240	2520		1120	560	280	140	70.00	35.00
290	0100100010	2175	2320	2610		1160	580	290	145	72.50	36.25
300	0100101100	2250	2400	2700		1200	600	300	150	75.00	37.50
310	0100110110	2325	2480			1240	620	310	155	77.50	38.75
320	0101000000	2400	2560			1280	640	320	160	80.00	40.00
330	0101001010	2475	2640			1320	660	330	165	82.50	41.25
340	0101010100	2550	2720			1360	680	340	170	85.00	42.50

Table 23. 8V43FS92432 Frequency Operating Range for P = 4

		f_{VCO} [MHz] (Parameter: f_{REF} in MHz)				Output Frequency for f_{XTAL} = 16 MHz (Parameter N)					
M	M[9:0]	15	16	18	20	2	4	8	16	32	64
340	0101010100		1360	1530	1700	680	340	170	85.0	42.50	21.25
350	0101011110		1400	1575	1750	700	350	175	87.5	43.75	21.875
360	0101101000		1440	1620	1800	720	360	180	90.0	45.00	22.50
370	0101110010	1387.5	1480	1665	1850	740	370	185	92.5	46.25	23.125
380	0101111100	1425.0	1520	1710	1900	760	380	190	95.0	47.50	23.75
390	0110000110	1462.5	1560	1755	1950	780	390	195	97.5	48.75	24.375
400	0110010000	1500.0	1600	1800	2000	800	400	200	100.0	50.00	25.00
410	0110110010	1537.5	1640	1845	2050	820	410	205	102.5	51.25	25.625
420	0110100100	1575.0	1680	1890	2100	840	420	210	105.0	52.50	26.25
430	0110101110	1612.5	1720	1935	2150	860	430	215	107.5	53.75	26.875
440	0110111000	1650.0	1760	1980	2200	880	440	220	110.0	55.00	27.50
450	0111000010	1687.5	1800	2025	2250	900	450	225	112.5	56.25	28.125
460	0111001100	1725.0	1840	2070	2300	920	460	230	115.0	57.50	28.75
470	0111010110	1762.5	1880	2115	2350	940	470	235	117.5	58.75	29.375
480	0111100000	1800.0	1920	2160	2400	960	480	240	120.0	60.00	30.00
490	0111101010	1837.5	1960	2205	2450	980	490	245	122.5	61.25	30.626
500	0111110100	1875.0	2000	2250	2500	1000	500	250	125.0	62.50	31.25
510	0111111110	1912.5	2040	2295	2550	1020	510	255	127.5	63.75	31.875
520	1000001000	1950.0	2080	2340	2600	1040	520	260	130.0	65.00	32.50
530	1000010010	1987.5	2120	2475	2650	1060	530	265	132.5	66.25	33.125
540	1000011100	2025.0	2160	2520	2700	1080	540	270	135.0	67.50	33.75
550	1000100110	2062.5	2200	2565		1100	550	285	137.5	68.75	34.375
560	1000110000	2100.0	2240	2610		1120	560	280	140.0	70.00	35.00
570	1000111010	2137.5	2280	2700		1140	570	285	142.5	71.25	35.625
580	1001000100	2175.0	2320			1160	580	290	145.0	72.50	36.25
590	1001001110	2212.5	2360			1180	590	295	147.5	73.75	36.875
600	1001011000	2250.0	2400			1200	600	300	150.0	75.00	37.50
610	1001100010	2287.5	2440			1220	610	305	152.5	76.25	38.125
620	1001101100	2325.0	2480			1240	620	310	155.0	77.50	38.75
630	1001110110	2362.5	2520			1260	630	315	157.5	78.75^	39.375
640	1010000000	2400.0	2560			1280	640	320	160.0	80.00	40.00
650	1010001010	2437.5	2600			1300	650	325	162.5	81.25	40.625
660	1010010100	2475.0	2640			1320	660	330	165	82.5	41.25
670	1010011110	2512.5	2680			1340	670	335	167.5	83.75	41.875
680	1010101000	2550.0	2720			1360	680	340	170	85.00	42.50

Applications Information

Recommendations for Unused Input and Output Pins

Inputs:

LVCMOS Control Pins

All control pins have internal pullup or pulldown resistors; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

Crystal Inputs

For applications not requiring the use of the crystal oscillator input, both XTAL1 and XTAL2 can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from XTAL_IN to ground.

Outputs:

LVPECL Outputs

All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

Overdriving the XTAL Interface

The XTAL_IN input can be overdriven by an LVCMOS driver or by one side of a differential driver through an AC coupling capacitor. The XTAL_OUT pin can be left floating. The amplitude of the input signal should be between 500mV and 1.8V and the slew rate should not be less than 0.2V/ns. For 3.3V LVCMOS inputs, the amplitude must be reduced from full swing to at least half the swing in order to prevent signal interference with the power rail and to reduce internal noise. Figure 5A shows an example of the interface diagram for a high speed 3.3V LVCMOS driver. This configuration requires that the sum of the output impedance of the driver (Ro) and the series resistance (Rs) equals the transmission line impedance. In addition, matched termination at the crystal input will attenuate the signal in half. This can be done in one of two ways. First, R1 and R2 in parallel should equal the transmission line impedance. For most 50Ω applications, R1 and R2 can be 100Ω. This can also be accomplished by removing R1 and changing R2 to 50Ω. The values of the resistors can be increased to reduce the loading for a slower and weaker LVCMOS driver. Figure 5B shows an example of the interface diagram for an LVPECL driver. This is a standard LVPECL termination with one side of the driver feeding the XTAL_IN input. It is recommended that all components in the schematics be placed in the layout. Though some components might not be used, they can be utilized for debugging purposes. The datasheet specifications are characterized and guaranteed by using a quartz crystal as the input.

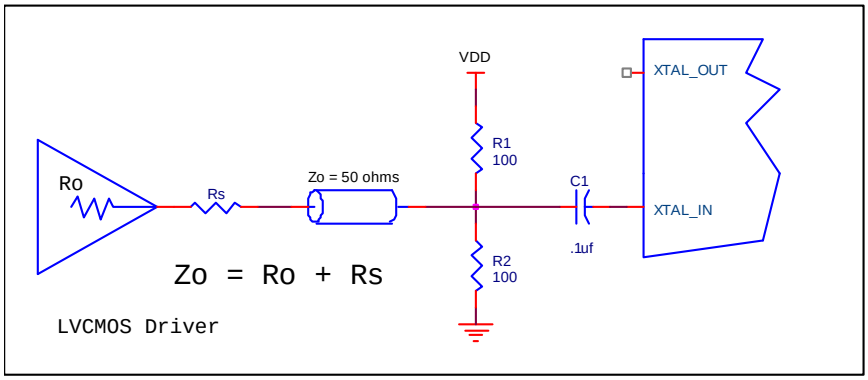


Figure 5A. General Diagram for LVCMOS Driver to XTAL Input Interface

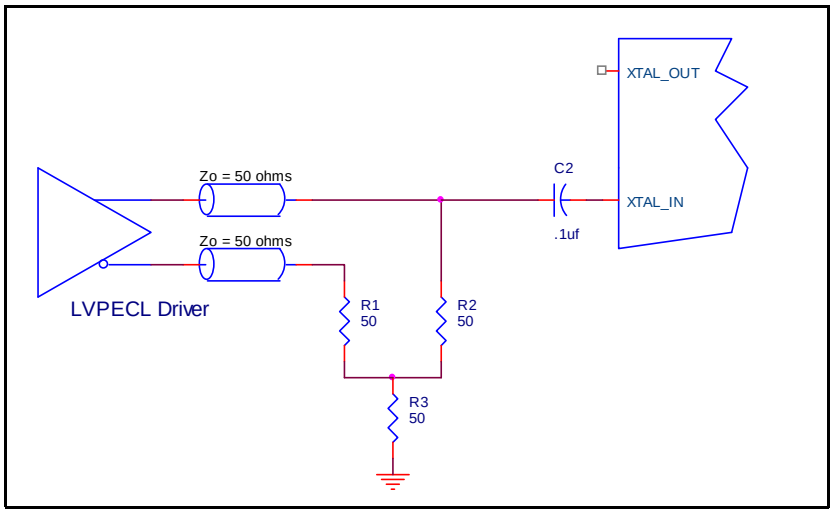


Figure 5B. General Diagram for LVPECL Driver to XTAL Input Interface

Termination for 3.3V LVPECL Outputs

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

The differential outputs are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figure 6A and* Figure 6B show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

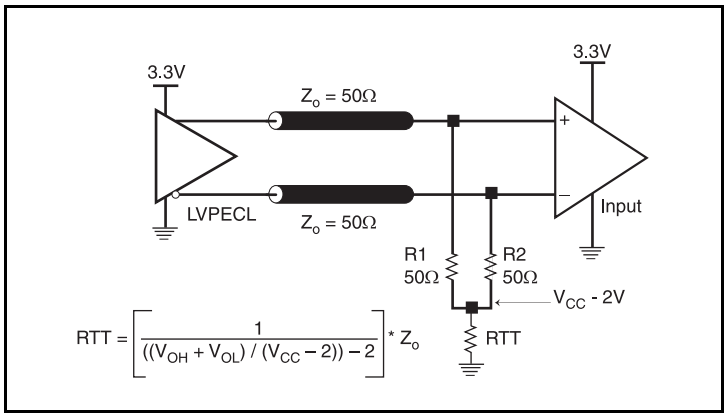


Figure 6A. 3.3V LVPECL Output Termination

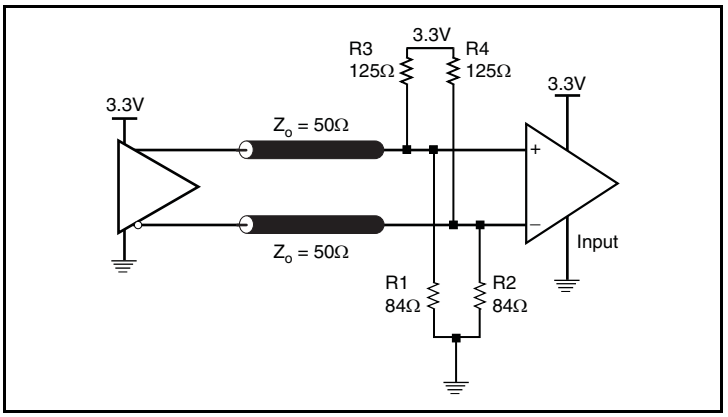


Figure 6B. 3.3V LVPECL Output Termination

Schematic Example

Figure 7 shows an example of 8V43FS92432 application schematic. In this example, the device is operated at V_{CC} = VCC_PLL = 3.3V. The schematic example focuses on functional connections and is not configuration specific. Refer to the pin description and functional tables in the datasheet to ensure that the logic control inputs are properly set.

A 12pF parallel resonant 20MHz crystal is used. For this device, the crystal load capacitors are required for proper operation. The load capacitance, C1 = C2 = 2pF, are recommended for frequency accuracy. Depending on the variation of the parasitic stray capacity of the printed circuit board traces between the crystal and the XTAL_IN and XTAL_OUT pins, the values of C1 and C2 might require a slight adjustment to optimize the frequency accuracy. Crystals with other load capacitance specifications can be used, but this will require adjusting C1 and C2. When designing the circuit board, return the capacitors to ground though a single point contact close to the package.

As with any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. The 8V43FS92432 provides separate power supplies to isolate any high switching noise from coupling into the internal PLL.

In order to achieve the best possible filtering, it is recommended that the placement of the filter components be on the device side of the PCB as close to the power pins as possible. If space is limited, the 0.1uF capacitor in each power pin filter should be placed on the device side. The other components can be on the opposite side of the PCB. Power supply filter recommendations are a general guideline to be used for reducing external noise from coupling into the devices. The filter performance is designed for a wide range of noise frequencies. This low-pass filter starts to attenuate noise at approximately 10kHz. If a specific frequency noise component is known, such as switching power supplies frequencies, it is recommended that component values be adjusted and if required, additional filtering be added. Additionally, good general design practices for power plane voltage stability suggests adding bulk capacitance in the local area of all devices.

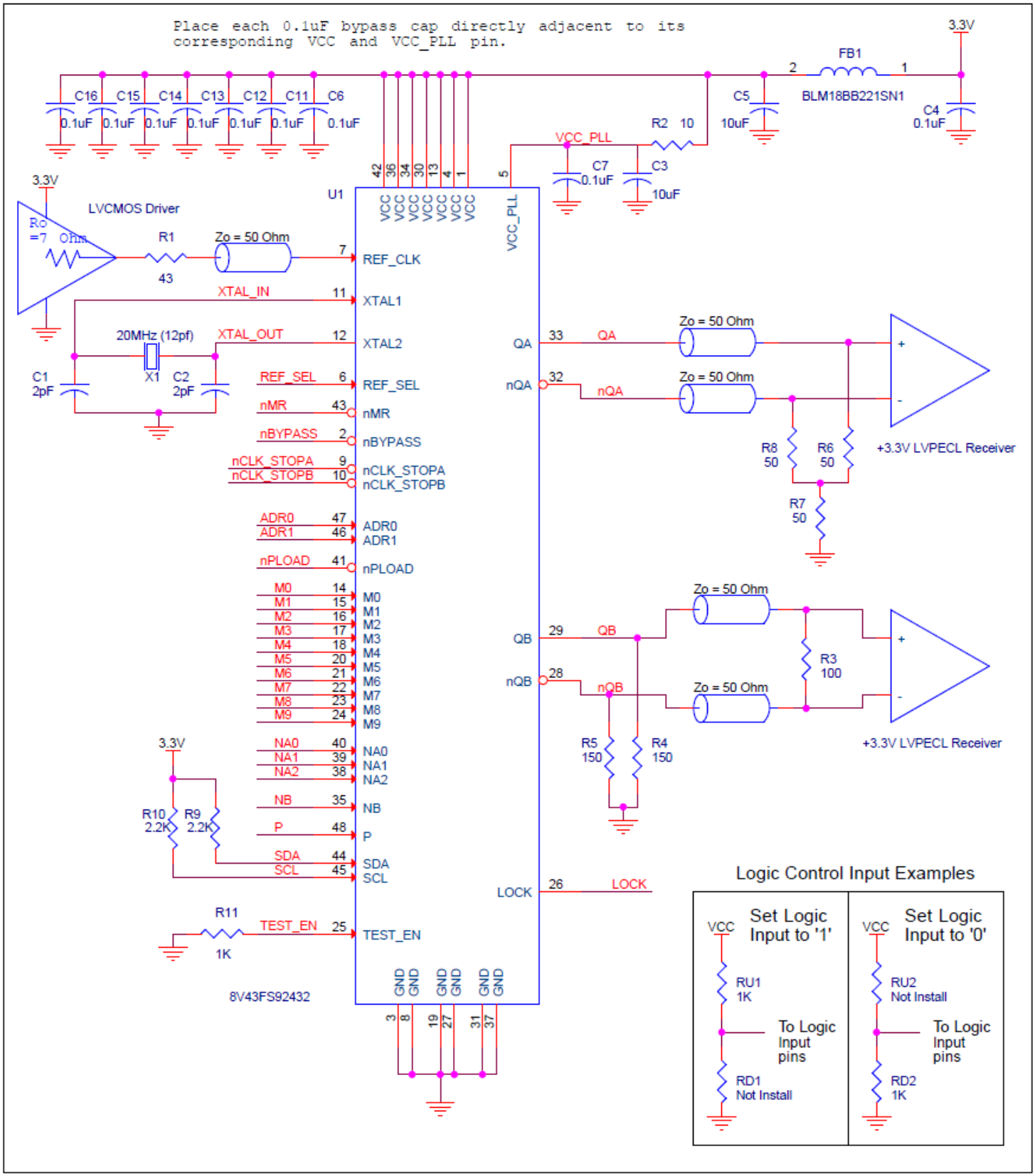


Figure 7. Signal I/O and Power Filters

Power Considerations

This section provides information on power dissipation and junction temperature for the 8V43FS92432.
Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the 8V43FS92432 is the sum of the core power plus the power dissipated due to the load.
The following is the power dissipation for V_{CC} = 3.3V + 5% = 3.465V, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- The maximum current is: I_{CC_max} = **165mA**
- Power (core)$_{MAX}$ = V_{CC_MAX} * I_{CC_MAX} = 3.465V * 165mA = **571.7mW**
- Power (outputs)$_{MAX}$ = **33.65mW/Loaded Output pair**
  If all outputs are loaded, the total power is 2 * 33.65mW = **67.3mW**

  Total Power$_{_MAX}$ (3.465V, with all outputs switching) = 571.7mW + 67.3mW = **639mW**

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature is 125°C. Limiting the internal transistor junction temperature, Tj, to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for Tj is as follows: $Tj = \theta_{JA} * Pd_total + T_A$

Tj = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming 1m/s air flow and a multi-layer board, the appropriate value is 60.4°C/W per Table 24 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

85°C + 0.639W * 60.4°C/W = 123.6°C. This is within the limit of 125°C.

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 24. Thermal Resistance θ_{JA} for 48-Lead LQFP, Forced Convection

θ_{JA} by Velocity			
Meters per Second	**0**	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	70.2°C/W	60.4°C/W	56.9°C/W

3. Calculations and Equations.

The purpose of this section is to calculate the power dissipation for the LVPECL output pairs.

LVPECL output driver circuit and termination are shown in Figure 8.

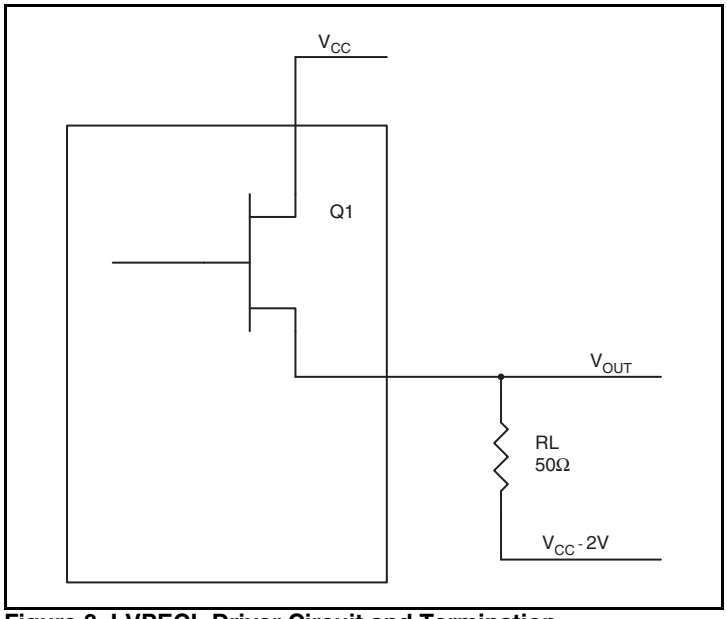


Figure 8. LVPECL Driver Circuit and Termination

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of V_{CC} – 2V.

- For logic high, $V_{OUT} = V_{OH_MAX} = \mathbf{V_{CC_MAX} - 0.74V}$
  $(V_{CC_MAX} - V_{OH_MAX}) = \mathbf{0.74V}$
- For logic low, $V_{OUT} = V_{OL_MAX} = \mathbf{V_{CC_MAX} - 1.5V}$
  $(V_{CC_MAX} - V_{OL_MAX}) = \mathbf{1.5V}$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$Pd_H = [(V_{OH_MAX} – (V_{CC_MAX} – 2V))/R_L] * (V_{CC_MAX} – V_{OH_MAX}) = [(2V – (V_{CC_MAX} – V_{OH_MAX}))/R_L] * (V_{CC_MAX} – V_{OH_MAX}) =$
$[(2V – 0.74V)/50Ω] * 0.74V =$ **18.65mW**

$Pd_L = [(V_{OL_MAX} – (V_{CC_MAX} – 2V))/R_L] * (V_{CC_MAX} – V_{OL_MAX}) = [(2V – (V_{CC_MAX} – V_{OL_MAX}))/R_{L]} * (V_{CC_MAX} – V_{OL_MAX}) =$
$[(2V – 1.5V)/50Ω] * 1.5V =$ **15mW**

Total Power Dissipation per output pair = Pd_H + Pd_L = **33.65mW**

Reliability Information

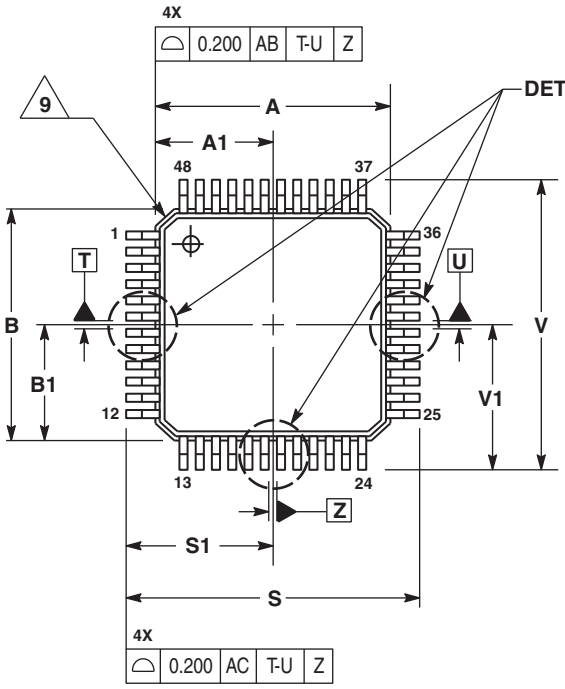
Table 25. θ_{JA} vs. Air Flow Table for a 48-Lead LQFP

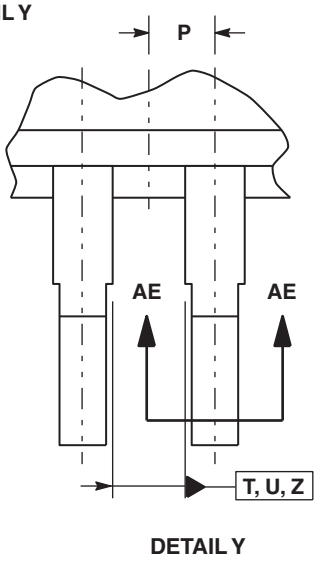
θ_{JA} Vs. Air Flow			
Meters per Second	**0**	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	70.2°C/W	60.4°C/W	56.9°C/W

Transistor Count

The transistor count for 8V43FS92432 is: 12,972

PACKAGE DIMENSIONS

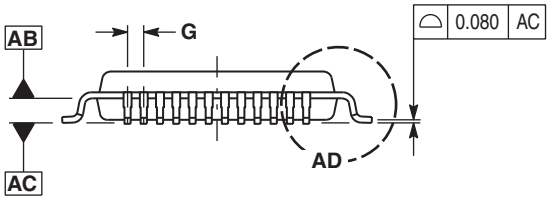


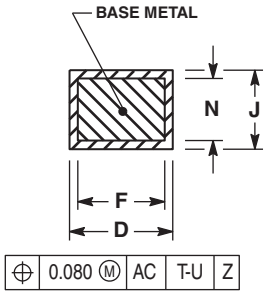


DETAIL Y

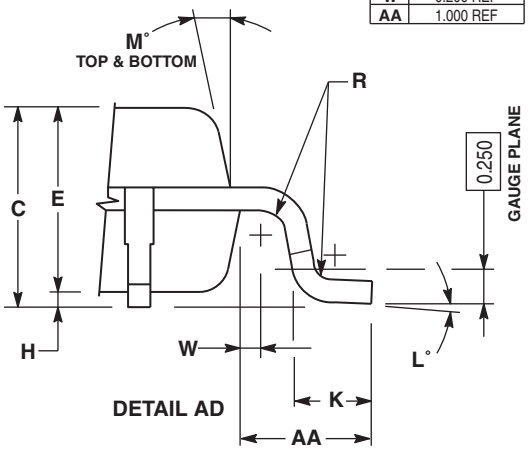
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5m, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLAN AB IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS T, U, AND Z TO BE DETERMINED AT DATAUM PLANE AB.
5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE AC.
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE AB.
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.350.
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076.
9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

	MILLIMETERS	
DIM	MIN	MAX
A	7.000 BSC	
A1	3.500 BSC	
B	7.000 BSC	
B1	3.500 BSC	
C	1.400	1.600
D	0.170	0.270
E	1.350	1.450
F	0.170	0.230
G	0.500 BSC	
H	0.050	0.150
J	0.090	0.200
K	0.500	0.700
L	0°	7°
M	12° REF	
N	0.090	0.160
P	0.250 BSC	
R	0.150	0.250
S	9.000 BSC	
S1	4.500 BSC	
V	9.000 BSC	
V1	4.500 BSC	
W	0.200 REF	
AA	1.000 REF	





SECTION AE-AE



DETAIL AD

CASE 932-03
ISSUE F
48-LEAD LQFP PACKAGE

Ordering Information

Table 24. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
8V43FS92432PRGI	IDT8V43FS92432PRGI	48 Lead LQFP, Lead-Free	Tube	–40°C to +85°C
8V43FS92432PRGI8	IDT8V43FS92432PRGI	48 Lead LQFP, Lead-Free	Tape & Reel	–40°C to +85°C

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